

Linear InGaAs sensors



512 pixel
25 x 250 μm rectangular pixel for spectroscopy
0.9 - 1.7 μm
around 40 kHz read out rate (t.b.d.)
28-pin DIP-metal package with 1-stage thermoelectric cooler

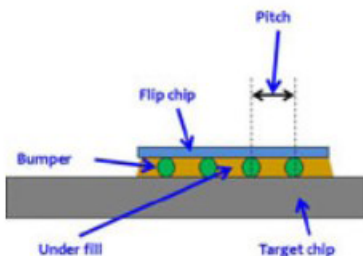
1024 Pixel
12.5 μm square Pixel
0.9 - 1.7 μm
around 40 kHz read out rate (t.b.d.)
28-pin DIP-metal package with 1-stage thermoelectric cooler

IR-extended 1.9 μm InGaAs-FPAs



QVGA (320 x 256) + VGA (640 x 512) pixel resolution
Compact 50 mm-Kovar-package with 2-stage TE-cooler and reduced power-consumption
SWAP – Small Weight and Power
Lower noise and less crosshatch-structures than 2.2 μm -InGaAs

Flip-Chip bond services



Bonding of Flip-Chip to Target-Chip with Indium-perls
For manufacturing of FPAs, LDAs, MEMS, BGAs, 3D-ICs, μLEDs



Visit us at VISION 2022
Stuttgart Messe, 04. - 06. October 2022
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